

FEATURES

- ✓ Protects 3.3, 5, 12, 15, 24 V Components
- ✓ Bidirectional
- ✓ Provides Electrically Isolated Protection
- ✓ IEC 61000-4-2 (ESD) 15kV(air), 8kV(contact)
- ✓ 300 W @ 8/20 μ s
- ✓ Protects 4 Lines
- ✓ SO-8 Packaging
- ✓ This is a Pb - Free Device
- ✓ All SMC parts are traceable to the wafer lot
- ✓ Additional testing can be offered upon request

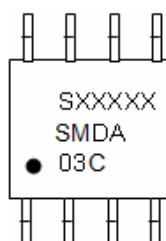
DESCRIPTION

The SMDAXXC series of TVS array have been designed to provide bidirectional protection for sensitive electronics from damage due to voltage transients caused by electrostatic discharge (ESD), electrical fast transients (EFT), lightning and other voltage-induced transient events. The device can be used to protect combinations of four bidirectional lines.

APPLICATION

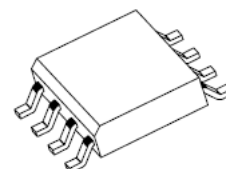
- ✓ RS-232 & RS-422 Data Lines
- ✓ Microprocessor Based Equipment
- ✓ Notebooks, Desktops, & Servers
- ✓ LAN/WAN Equipment
- ✓ Serial and Parallel Port
- ✓ Peripherals

MARKING DIAGRAM



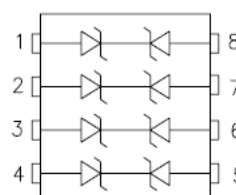
Cautions: Molding resin
Epoxy resin UL:94V-0

SO-8



TVS ARRAY SERIES

SCHEMATIC & PIN CONFIGURATION



MECHANICAL CHARACTERISTICS

- ✓ SO-8 Surface Mount Package
- ✓ Approximate Weight: 0.1 grams
- ✓ PIN #1 Indicator: DOT on top of package
- ✓ Packaging: Tubes or Tape & Reel per EIA Standard 481

Where XXXXX is YYWWL

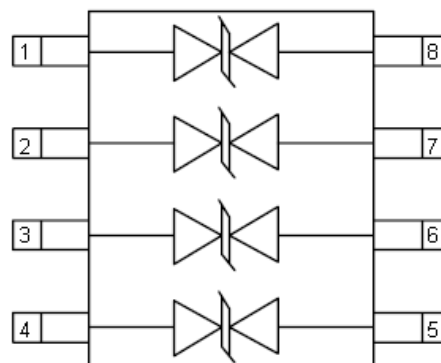
SMDA03C = Part Name
S = S
YY = Year
WW = Week
L = Lot Number



Circuit Diagram

The SMDAxxC series of devices are designed to protect up to four data lines. The devices are connected as follows:

- ✓ The SMDAxxC are bidirectional devices and are designed for use on line where the normal operating voltage is above ground. Pins 1, 2, 3, and 4 are connected to the protected lines. Pins 5, 6, 7, and 8 are connected to ground. Since the device is electrically symmetrical, these connections may be reversed. The ground connections should be made directly to the ground plane for best results. The path length is kept as short as possible to reduce the effects of parasitic inductance in the board traces.



Ordering Information:

Device	Package	Shipping
SMDA03C THRU SMDA24C	SO-8 (Pb-Free)	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

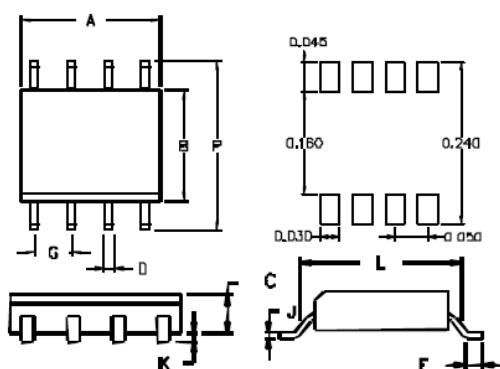
ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
P	Peak Pulse Power, 8/20 μ s Waveshape	300	W
T _J	Operating Temperature	-55 to +125	°C
T _{STG}	Storage Temperature	-55 to +150	°C
T _L	Lead Soldering Temperature	260 (10 Sec.)	°C

ELECTRICAL CHARACTERISTICS @ 25 °C

Part Number	Stand-off Voltage V_{WM} (V) Max	Breakdown Voltage V_{BR} @1mA (V) Min	Clamping Voltage V_C @ 1 A (V) Max	Leakage Current I_R @ V_{WM} (μ A) Max	Capacitance (f = 1 MHz) C @ 0V (pF) Max	Temperature Coefficient of V_{BR} $a(V_{BR})$ mV/°C Max
SMDA03C	3.3	4	7	200	400	-5
SMDA05C	5.0	6	9.8	40	300	1
SMDA12C	12.0	13.3	19	1	94	8
SMDA15C	15.0	16.7	24	1	70	11
SMDA24C	24.0	26.7	43	1	45	28

PACKAGE OUTLINES & DIMENSIONS



DIM	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.189	0.196	4.8	5.0
B	0.150	0.157	3.8	4.0
C	0.053	0.069	1.35	1.75
D	0.011	0.021	0.28	0.53
F	0.016	0.050	0.41	1.27
G	0.050 BSC		1.27 BSC	
J	0.006	0.010	0.15	0.25
K	0.004	0.008	0.10	0.20
L	0.189	0.206	4.80	5.23
P	0.228	0.244	5.79	6.19

TYPICAL CHARACTERISTICS

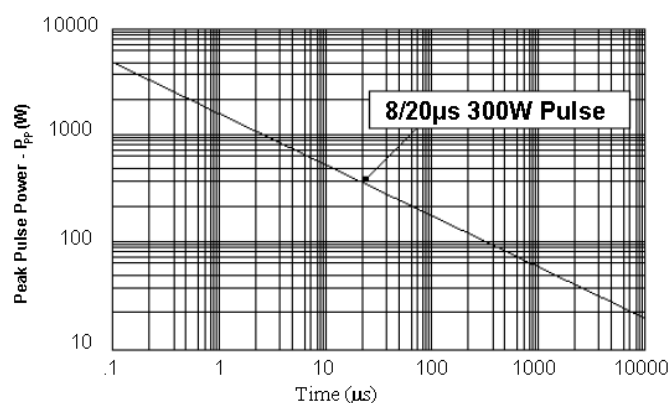


Figure 1. Peak Pulse Power Vs Pulse Time (μs)

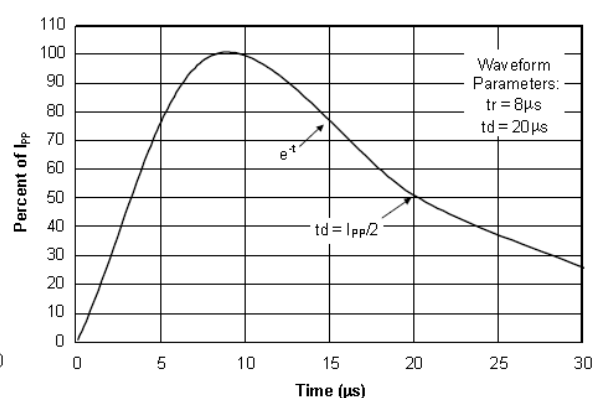


Figure 2. Pulse Wave Form



**SMDA03C
THRU
SMDA24C**

**Technical Data
Data Sheet N0297, Rev. A**

Green Products

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